

PDS4200H-13 PDS5100H-13 PDS835L-13 PDS3200-13 PDS4150-13 PDS760-13 PDS1040-13 PDS1040C- PDS1040L-13 PDS1045-13

Part Number:
Weight (mg): 100.6573

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Si, Doped	7440-21-3	100.00%	4.06	4.0873	1000000	40606
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	3.48	3.5063	925000	32221
		Sn	7440-31-5	5.00%			50000	1742
		Ag	7440-22-4	2.50%			25000	871
Leadframe & Clip	Copper Alloy	Copper	7440-50-8	97.40%	63.34	63.7526	974000	616895
		Fe	7439-89-6	2.40%			24000	15201
		Phosphorus	7723-14-0	0.08%			800	507
		Zn	7440-66-6	0.12%			1200	760
Die Pad Plating	Silver	Ag	7440-22-4	100.00%	0.91	0.9135	1000000	9075
Encapsulation	Epoxy EME-G700L	Epoxy Resin	-----	7.00%	26.73	26.9008	70000	18708
		Phenol Resin	-----	5.00%			50000	13363
		Bismuth/Bismuth compound	-----	0.05%			500	134
		SiO2	60676-86-0	87.45%			874500	233711
		C	1333-86-4	0.50%			5000	1336
Lead Plating Finish	Tin Solder	Sn (>99.5%)	7440-31-5	100.00%	1.49	1.4968	1000000	14870
				Total	100.00	100.66		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness. See the applicable Data Sheet for any Date Code limits.

^ The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables o

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Organic tin compounds
Antimony Compounds	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)

REACH SVHCs:

Anthracene	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
4,4'- Diaminodiphenylmethane	Bis (2-ethyl(hexyl)phthalate) (DEHP)
Dibutyl phthalate	Hexabromocyclododecane (HBCDD)
Cyclododecane	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cobalt dichloride	Bis(tributyltin)oxide
Diarsenic pentaoxide	Lead hydrogen arsenate
Diarsenic trioxide	Triethyl arsenate
Sodium dichromate, dihydrate	Benzyl butyl phthalate

PDS340-13 PDS360-13 PDS540-13 PDS560-13 PDS3100-13 PDS5100-13

Part Number:
Weight (mg): 98.84

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Si, Doped	7440-21-3	100.00%	2.03	2.01	1000000	20329
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	1.75	1.73	925000	16180
		Sn	7440-31-5	5.00%			50000	875
		Ag	7440-22-4	2.50%			25000	437
Leadframe & Clip	Copper Alloy	Copper	7440-50-8	97.40%	64.50	63.75	974000	628259
		Fe	7439-89-6	2.40%			24000	15481
		Phosphorus	7723-14-0	0.08%			800	516
		Zn	7440-66-6	0.12%			1200	774
Die Pad Plating	Silver	Ag	7440-22-4	100.00%	0.92	0.91	1000000	9243
Encapsulation	Epoxy EME-G700L	Epoxy Resin	-----	7.00%	29.28	28.94	70000	20493
		Phenol Resin	-----	5.00%			50000	14638
		Bismuth/Bismuth compound	-----	0.05%			500	146
		SiO2	60676-86-0	87.45%			874500	256021
		C	1333-86-4	0.50%			5000	1464
Lead Plating Finish	Tin Solder	Sn (>99.5%)	7440-31-5	100.00%	1.51	1.50	1000000	15144
				Total	100.00	98.84		1000000

Tolerance ±10%

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| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
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|------------------------------|---|
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| Diarsenic pentaoxide | Lead hydrogen arsenate |
| Diarsenic trioxide | Triethyl arsenate |
| Sodium dichromate, dihydrate | Benzyl butyl phthalate |